

SID

Factory: Rot am See

Article:

532

ML4

Provided:

Kracht, Enrico

Customer:

Date:

22.09.2015



Processtechnology: B: undefiniert

Material Text	Mat. Nr.	µm	Stackup	Process overview
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A-RS Kupferfolie-035my 330x490mm	50200242	35	VS	1	A00 B00
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	170		2	
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	0		3	
A-RS-FR4-ML-0.20mm-035+035-TG150-HF	50200653	35	L2	4	
		200			
		35	L3		
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	170		5	
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	0		6	
A-RS Kupferfolie-035my 330x490mm	50200242	35	RS	7	

Thickness after Pressing

B00:

690 µm

Tol+:

80 µm

Tol-:

80 µm

Dmax:

770 µm

Dmin:

610 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

800 µm

Tol+:

80 µm

Tol-:

80 µm

Dmax:

880 µm

Dmin:

720 µm

Measuring point: (05) über LM und galv.Cu; beidseitig

nominal:

680 µm

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